

E UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Andrew Marshall

Docket No.: TI-31484

Serial No.: 10/007,332

Art Unit: 2815

Filed: 11/08/01

Examiner: Warren, M. E.

Title: Thermal Coupling of Matched SOI Device Bodies

AMENDMENT UNDER 37 CFR 1.111

May 12, 2004

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on 5-12-04

as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Karen Vert 5-12-04

In response to the Office Action, dated 02/17/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.